Claims

1. A flex interconnection circuit substrate, comprising:

a connector bonding site coupled to an electronic component collection bonding site; and

said electronic component collection bonding site coupled to at least one MR read-write head bonding site;

wherein said electronic component collection includes at least one preamplifier.

2. The apparatus of Claim 11,

wherein said electronic components collection further includes at least one member of the collection comprising a resistor and a capacitor.

3. A flex interconnection circuit, comprising:

said flex interconnection circuit substrate of Claim 11;

a connector bonded to said connector bonding site;

said electronics component collection bonded to said electronics component collection bonding site comprising at least said preamplifier bonded to said electronic component bonding site; and

at least one MR read-write head bonded to said MR read-write head bonding site;

wherein said flex interconnection circuit couples said connector and said preamplifier;

wherein said flex interconnection circuit couples said preamplifier and said MR read-write head.

4. Said flex interconnection circuit of Claim 13, further comprising:

a second MR read-write head bonded to said MR read-write head bonding site;

wherein said flex interconnection circuit couples said preamplifier and said second MR read-write head.

5. An actuator, comprising:

a head slider affixed with said MR read-write head of said flex interconnection circuit of Claim 13;

said flex interconnection circuit anchored about said preamplifier to said actuator; and

at least one binding of said flex interconnection circuit between said preamplifier and said MR read-write head.

6. A disk drive, comprising:

said actuator of Claim 15 coupled by said connector to a disk drive controller printed circuit board.